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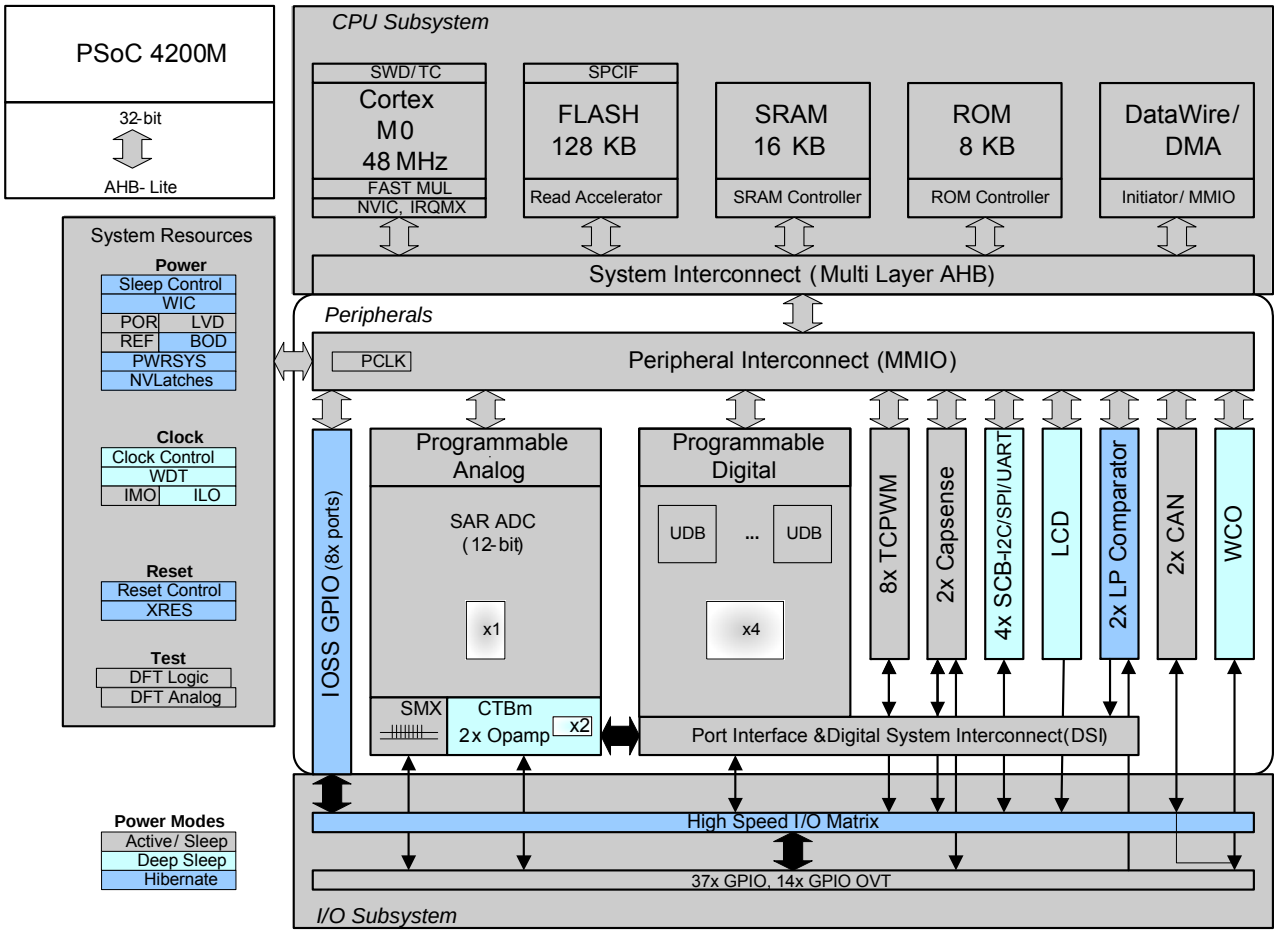
What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	ARM® Cortex®-M0
Core Size	32-Bit Single-Core
Speed	48MHz
Connectivity	CANbus, I²C, IrDA, LINbus, Microwire, SmartCard, SPI, SSP, UART/USART
Peripherals	Brown-out Detect/Reset, Cap Sense, LCD, LVD, POR, PWM, SmartSense, WDT
Number of I/O	51
Program Memory Size	128KB (128K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	16K x 8
Voltage - Supply (Vcc/Vdd)	1.71V ~ 5.5V
Data Converters	A/D 16x12b SAR; D/A 4x8b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-LQFP
Supplier Device Package	64-TQFP (14x14)
Purchase URL	https://www.e-xfl.com/product-detail/infineon-technologies/cy8c4247axi-m485

PSoC 4200M Block Diagram



The PSoC 4200-M devices include extensive support for programming, testing, debugging, and tracing both hardware and firmware.

The ARM Serial_Wire Debug (SWD) interface supports all programming and debug features of the device.

Complete debug-on-chip functionality enables full-device debugging in the final system using the standard production device. It does not require special interfaces, debugging pods, simulators, or emulators. Only the standard programming connections are required to fully support debug.

The PSoC Creator Integrated Development Environment (IDE) provides fully integrated programming and debug support for PSoC 4200-M devices. The SWD interface is fully compatible with industry-standard third-party tools. The PSoC 4200-M family provides a level of security not possible with multi-chip application solutions or with microcontrollers. This is due to its ability to disable debug features, robust flash protection, and because it allows customer-proprietary functionality to be implemented in on-chip programmable blocks.

The debug circuits are enabled by default and can only be disabled in firmware. If not enabled, the only way to re-enable them is to erase the entire device, clear flash protection, and reprogram the device with new firmware that enables debugging.

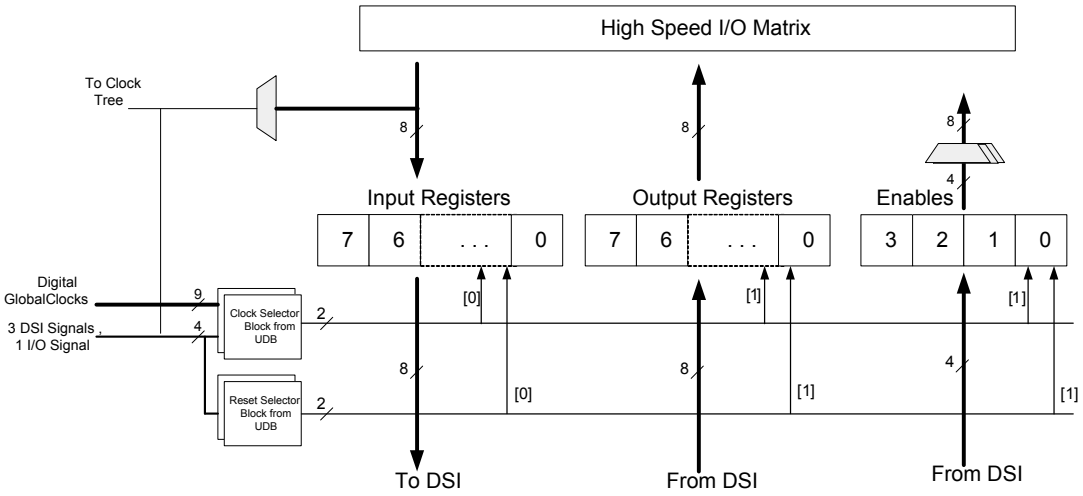
Additionally, all device interfaces can be permanently disabled (device security) for applications concerned about phishing attacks due to a maliciously reprogrammed device or attempts to defeat security by starting and interrupting flash programming sequences. Because all programming, debug, and test interfaces are disabled when maximum device security is enabled, PSoC 4200-M with device security enabled may not be returned for failure analysis. This is a trade-off the PSoC 4200-M allows the customer to make.

UDBs can be clocked from a clock divider block, from a port interface (required for peripherals such as SPI), and from the DSI network directly or after synchronization.

A port interface is defined, which acts as a register that can be clocked with the same source as the PLDs inside the UDB array. This allows faster operation because the inputs and outputs can be registered at the port interface close to the I/O pins and at the edge of the array. The port interface registers can be clocked by one of the I/Os from the same port. This allows interfaces such as SPI to operate at higher clock speeds by eliminating the delay for the port input to be routed over DSI and used to register other inputs. The port interface is shown in Figure 6.

The UDBs can generate interrupts (one UDB at a time) to the interrupt controller. The UDBs can connect to any pin on Ports 0, 1, 2, and 3 (each port interconnect requires one UDB) through the DSI.

Figure 6. Port Interface



Fixed Function Digital

Timer/Counter/PWM (TCPWM) Block

The TCPWM block uses a16-bit counter with user-programmable period length. There is a Capture register to record the count value at the time of an event (which may be an I/O event), a period register which is used to either stop or auto-reload the counter when its count is equal to the period register, and compare registers to generate compare value signals, which are used as PWM duty cycle outputs. The block also provides true and complementary outputs with programmable offset between them to allow use as deadband programmable complementary PWM outputs. It also has a Kill input to force outputs to a predetermined state; for example, this is used in motor drive systems when an overcurrent state is indicated and the PWMs driving the FETs need to be shut off immediately with no time for software intervention. The PSoC 4200M has eight TCPWM blocks.

Serial Communication Blocks (SCB)

The PSoC 4200M has four SCBs, which can each implement an I^2C, UART, or SPI interface.

I^2C Mode: The hardware I^2C block implements a full multi-master and slave interface (it is capable of multimaster arbitration). This block is capable of operating at speeds of up to 1 Mbps (Fast Mode Plus) and has flexible buffering options to reduce interrupt overhead and latency for the CPU. It also supports EzI^2C that creates a mailbox address range in the memory of the PSoC 4200M and effectively reduces I^2C communication to reading from and writing to an array in memory. In addition, the block supports an 8-deep FIFO for receive and transmit which, by increasing the time given for the CPU to read data, greatly reduces the need for clock stretching caused by the CPU not having read data on time. The FIFO mode is available in all channels and is very useful in the absence of DMA.

The I^2C peripheral is compatible with the I^2C Standard-mode, Fast-mode, and Fast-mode Plus devices as defined in the NXP I^2C-bus specification and user manual (UM10204). The I^2C bus I/O is implemented with GPIO in open-drain modes.

UART Mode: This is a full-feature UART operating at up to 1 Mbps. It supports automotive single-wire interface (LIN), infrared interface (IrDA), and SmartCard (ISO7816) protocols, all of which are minor variants of the basic UART protocol. In addition, it supports the 9-bit multiprocessor mode that allows addressing of peripherals connected over common RX and TX lines. Common UART functions such as parity error, break detect, and frame error are supported. An 8-deep FIFO allows much greater CPU service latencies to be tolerated.

SPI Mode: The SPI mode supports full Motorola SPI, TI SSP (essentially adds a start pulse used to synchronize SPI Codecs), and National Microwire (half-duplex form of SPI). The SPI block can use the FIFO and also supports an EzSPI mode in which data interchange is reduced to reading and writing an array in memory.

CAN Blocks

There are two independent CAN 2.0B blocks, which are certified CAN conformant.

Pinouts

The following is the pin list for the PSoC 4200M. This shows the power supply and port pins (for example, P0.0 is Pin 0 of Port 0).

68-QFN		64-TQFP		48-TQFP		44-TQFP	
Pin	Name	Pin	Name	Pin	Name	Pin	Name
42	P0.0	39	P0.0	28	P0.0	24	P0.0
43	P0.1	40	P0.1	29	P0.1	25	P0.1
44	P0.2	41	P0.2	30	P0.2	26	P0.2
45	P0.3	42	P0.3	31	P0.3	27	P0.3
46	P0.4	43	P0.4	32	P0.4	28	P0.4
47	P0.5	44	P0.5	33	P0.5	29	P0.5
48	P0.6	45	P0.6	34	P0.6	30	P0.6
49	P0.7	46	P0.7	35	P0.7	31	P0.7
50	XRES	47	XRES	36	XRES	32	XRES
51	VCCD	48	VCCD	37	VCCD	33	VCCD
52	VSSD	49	VSSD	38	VSSD	DN	VSSD
53	VDDD	50	VDDD	39	VDDD	34	VDDD
				40	VDDA	35	VDDA
54	P5.0	51	P5.0				
55	P5.1	52	P5.1				
56	P5.2	53	P5.2				
57	P5.3	54	P5.3				
58	P5.4						
59	P5.5	55	P5.5				
60	VDDA	56	VDDA	40	VDDA	35	VDDA
61	VSSA	57	VSSA	41	VSSA	36	VSSA
62	P1.0	58	P1.0	42	P1.0	37	P1.0
63	P1.1	59	P1.1	43	P1.1	38	P1.1
64	P1.2	60	P1.2	44	P1.2	39	P1.2
65	P1.3	61	P1.3	45	P1.3	40	P1.3
66	P1.4	62	P1.4	46	P1.4	41	P1.4
67	P1.5	63	P1.5	47	P1.5	42	P1.5
68	P1.6	64	P1.6	48	P1.6	43	P1.6
1	P1.7/VREF	1	P1.7/VREF	1	P1.7/VREF	44	P1.7/VREF
						1	VSSD
2	P2.0	2	P2.0	2	P2.0	2	P2.0
3	P2.1	3	P2.1	3	P2.1	3	P2.1
4	P2.2	4	P2.2	4	P2.2	4	P2.2
5	P2.3	5	P2.3	5	P2.3	5	P2.3
6	P2.4	6	P2.4	6	P2.4	6	P2.4
7	P2.5	7	P2.5	7	P2.5	7	P2.5

68-QFN		64-TQFP		48-TQFP		44-TQFP	
Pin	Name	Pin	Name	Pin	Name	Pin	Name
8	P2.6	8	P2.6	8	P2.6	8	P2.6
9	P2.7	9	P2.7	9	P2.7	9	P2.7
10	VSSA	10	VSSA	10	VSSD	10	VSSD
11	VDDA	11	VDDA				
12	P6.0	12	P6.0				
13	P6.1	13	P6.1				
14	P6.2	14	P6.2				
15	P6.3						
16	P6.4	15	P6.4				
17	P6.5	16	P6.5				
18	VSSIO	17	VSSIO	10	VSSD	10	VSSD
19	P3.0	18	P3.0	12	P3.0	11	P3.0
20	P3.1	19	P3.1	13	P3.1	12	P3.1
21	P3.2	20	P3.2	14	P3.2	13	P3.2
22	P3.3	21	P3.3	16	P3.3	14	P3.3
23	P3.4	22	P3.4	17	P3.4	15	P3.4
24	P3.5	23	P3.5	18	P3.5	16	P3.5
25	P3.6	24	P3.6	19	P3.6	17	P3.6
26	P3.7	25	P3.7	20	P3.7	18	P3.7
27	VDDIO	26	VDDIO	21	VDDIO	19	VDDD
28	P4.0	27	P4.0	22	P4.0	20	P4.0
29	P4.1	28	P4.1	23	P4.1	21	P4.1
30	P4.2	29	P4.2	24	P4.2	22	P4.2
31	P4.3	30	P4.3	25	P4.3	23	P4.3
32	P4.4	31	P4.4				
33	P4.5	32	P4.5				
34	P4.6	33	P4.6				
35	P4.7						
39	P7.0	37	P7.0	26	P7.0		
40	P7.1	38	P7.1	27	P7.1		
41	P7.2						

The pins of Port 6 are overvoltage-tolerant. Pins 36, 37, and 38 are No-Connects on the 68-pin QFN. Pins 34, 35, and 36 are No-Connects on the 64-pin TQFP. Pins 11 and 15 are No-connects in the 48-pin TQFP. All VSS pins must be tied together.

The output drivers of I/O Ports P0 and P7 are connected to VDDD. Output drivers of I/O Ports 1, 2, and 5 are connected to VDDA. Output drivers of I/O Ports 3, 4, and 6 are connected to VDDIO.

Each of the pins shown in the previous table can have multiple programmable functions as shown in the following table. Column headings refer to Analog and Alternate pin functions.:

Port/Pin	Analog	Alt. Function 1	Alt. Function 2	Alt. Function 3	Alt. Function 4	Alt. Function 5
P0.0	lpcomp.in_p[0]			can[1].can_rx:0		scb[0].spi_select1:0
P0.1	lpcomp.in_n[0]			can[1].can_tx:0		scb[0].spi_select2:0
P0.2	lpcomp.in_p[1]					scb[0].spi_select3:0
P0.3	lpcomp.in_n[1]					
P0.4	wco_in		scb[1].uart_rx:0		scb[1].i2c_scl:0	scb[1].spi_mosi:1
P0.5	wco_out		scb[1].uart_tx:0		scb[1].i2c_sda:0	scb[1].spi_miso:1
P0.6		ext_clk:0	scb[1].uart_cts:0			scb[1].spi_clk:1
P0.7			scb[1].uart_rts:0	can[1].can_tx_enb_n:0	wakeup	scb[1].spi_select0:1
P5.0	ctb1.oa0.inp	tcpwm.line[4]:2	scb[2].uart_rx:0		scb[2].i2c_scl:0	scb[2].spi_mosi:0
P5.1	ctb1.oa0.inm	tcpwm.line_compl[4]:2	scb[2].uart_tx:0		scb[2].i2c_sda:0	scb[2].spi_miso:0
P5.2	ctb1.oa0.out	tcpwm.line[5]:2	scb[2].uart_cts:0		lpcomp.comp[0]:1	scb[2].spi_clk:0
P5.3	ctb1.oa1.out	tcpwm.line_compl[5]:2	scb[2].uart_rts:0		lpcomp.comp[1]:1	scb[2].spi_select0:0
P5.4	ctb1.oa1.inm	tcpwm.line[6]:2				scb[2].spi_select1:0
P5.5	ctb1.oa1.inp	tcpwm.line_compl[6]:2				scb[2].spi_select2:0
P5.6	ctb1.oa0.inp_alt	tcpwm.line[7]:0				scb[2].spi_select3:0
P5.7	ctb1.oa1.inp_alt	tcpwm.line_compl[7]:0				
P1.0	ctb0.oa0.inp	tcpwm.line[2]:1	scb[0].uart_rx:1		scb[0].i2c_scl:0	scb[0].spi_mosi:1
P1.1	ctb0.oa0.inm	tcpwm.line_compl[2]:1	scb[0].uart_tx:1		scb[0].i2c_sda:0	scb[0].spi_miso:1
P1.2	ctb0.oa0.out	tcpwm.line[3]:1	scb[0].uart_cts:1			scb[0].spi_clk:1
P1.3	ctb0.oa1.out	tcpwm.line_compl[3]:1	scb[0].uart_rts:1			scb[0].spi_select0:1
P1.4	ctb0.oa1.inm	tcpwm.line[6]:1				scb[0].spi_select1:1
P1.5	ctb0.oa1.inp	tcpwm.line_compl[6]:1				scb[0].spi_select2:1
P1.6	ctb0.oa0.inp_alt	tcpwm.line[7]:1				scb[0].spi_select3:1
P1.7	ctb0.oa1.inp_alt	tcpwm.line_compl[7]:1				
P2.0	sarmux.0	tcpwm.line[4]:1			scb[1].i2c_scl:1	scb[1].spi_mosi:2
P2.1	sarmux.1	tcpwm.line_compl[4]:1			scb[1].i2c_sda:1	scb[1].spi_miso:2
P2.2	sarmux.2	tcpwm.line[5]:1				scb[1].spi_clk:2
P2.3	sarmux.3	tcpwm.line_compl[5]:1				scb[1].spi_select0:2
P2.4	sarmux.4	tcpwm.line[0]:1				scb[1].spi_select1:1
P2.5	sarmux.5	tcpwm.line_compl[0]:1				scb[1].spi_select2:1
P2.6	sarmux.6	tcpwm.line[1]:1				scb[1].spi_select3:1

Power

The supply voltage range is 1.71 to 5.5 V with all functions and circuits operating over that range.

The PSoC 4200M family allows two distinct modes of power supply operation: Unregulated External Supply and Regulated External Supply modes.

Unregulated External Supply

In this mode, the PSoC 4200M is powered by an External Power Supply that can be anywhere in the range of 1.8 to 5.5 V. This range is also designed for battery-powered operation, for instance, the chip can be powered from a battery system that starts at 3.5V and works down to 1.8 V. In this mode, the internal regulator of the PSoC 4200M supplies the internal logic and the VCCD output of the PSoC 4200M must be bypassed to ground via an external Capacitor (in the range of 1 to 1.6 µF; X5R ceramic or better).

The grounds, VSSA and VSS, must be shorted together. Bypass capacitors must be used from VDDD and VDDA to ground, typical practice for systems in this frequency range is to use a capacitor in the 1 µF range in parallel with a smaller capacitor (0.1 µF, for example). Note that these are simply rules of thumb and that, for critical applications, the PCB layout, lead inductance, and the Bypass capacitor parasitic should be simulated to design and obtain optimal bypassing.

Power Supply	Bypass Capacitors
VDDD–VSS and VDDIO-VSS	0.1 µF ceramic at each pin plus bulk capacitor 1 to 10 µF.
VDDA–VSSA	0.1 µF ceramic at pin. Additional 1 µF to 10 µF bulk capacitor
VCCD–VSS	1 µF ceramic capacitor at the VCCD pin
VREF–VSSA (optional)	The internal bandgap may be bypassed with a 1 µF to 10 µF capacitor for better ADC performance.

Regulated External Supply

In this mode, the PSoC 4200M is powered by an external power supply that must be within the range of 1.71 to 1.89 V (1.8 ±5%); note that this range needs to include power supply ripple. VCCD and VDDD pins are shorted together and bypassed. The internal regulator is disabled in firmware.

Development Support

The PSoC 4200M family has a rich set of documentation, development tools, and online resources to assist you during your development process. Visit www.cypress.com/go/psoc4 to find out more.

Documentation

A suite of documentation supports the PSoC 4200M family to ensure that you can find answers to your questions quickly. This section contains a list of some of the key documents.

Software User Guide: A step-by-step guide for using PSoC Creator. The software user guide shows you how the PSoC Creator build process works in detail, how to use source control with PSoC Creator, and much more.

Component Datasheets: The flexibility of PSoC allows the creation of new peripherals (components) long after the device has gone into production. Component data sheets provide all of the information needed to select and use a particular component, including a functional description, API documentation, example code, and AC/DC specifications.

Application Notes: PSoC application notes discuss a particular application of PSoC in depth; examples include brushless DC motor control and on-chip filtering. Application notes often include example projects in addition to the application note document.

Technical Reference Manual: The Technical Reference Manual (TRM) contains all the technical detail you need to use a PSoC device, including a complete description of all PSoC registers.

Online

In addition to print documentation, the Cypress PSoC forums connect you with fellow PSoC users and experts in PSoC from around the world, 24 hours a day, 7 days a week.

Tools

With industry standard cores, programming, and debugging interfaces, the PSoC 4200M family is part of a development tool ecosystem. Visit us at www.cypress.com/go/psoccreator for the latest information on the revolutionary, easy to use PSoC Creator IDE, supported third party compilers, programmers, debuggers, and development kits.

Table 2. DC Specifications *(continued)*

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details / Conditions
Deep Sleep Mode, –40 °C to + 60 °C							
SID30	I_{DD25}	I^2C wakeup and WDT on. Regulator Off.	–	1.55	20	µA	V_{DD} = 1.71 to 1.89
SID31	I_{DD26}	I^2C wakeup and WDT on.	–	1.35	15	µA	V_{DD} = 1.8 to 3.6
SID32	I_{DD27}	I^2C wakeup and WDT on.	–	1.5	15	µA	V_{DD} = 3.6 to 5.5
Deep Sleep Mode, +85 °C							
SID33	I_{DD28}	I^2C wakeup and WDT on. Regulator Off.	–	–	60	µA	V_{DD} = 1.71 to 1.89
SID34	I_{DD29}	I^2C wakeup and WDT on.	–	–	45	µA	V_{DD} = 1.8 to 3.6
SID35	I_{DD30}	I^2C wakeup and WDT on.	–	–	30	µA	V_{DD} = 3.6 to 5.5
Deep Sleep Mode, +105 °C							
SID33Q	I_{DD28Q}	I^2C wakeup and WDT on. Regulator Off.	–	–	135	µA	V_{DD} = 1.71 to 1.89
SID34Q	I_{DD29Q}	I^2C wakeup and WDT on.	–	–	180	µA	V_{DD} = 1.8 to 3.6
SID35Q	I_{DD30Q}	I^2C wakeup and WDT on.	–	–	140	µA	V_{DD} = 3.6 to 5.5
Hibernate Mode, –40 °C to + 60 °C							
SID39	I_{DD34}	Regulator Off.	–	150	3000	nA	V_{DD} = 1.71 to 1.89
SID40	I_{DD35}		–	150	1000	nA	V_{DD} = 1.8 to 3.6
SID41	I_{DD36}		–	150	1100	nA	V_{DD} = 3.6 to 5.5
Hibernate Mode, +85 °C							
SID42	I_{DD37}	Regulator Off.	–	–	4500	nA	V_{DD} = 1.71 to 1.89
SID43	I_{DD38}		–	–	3500	nA	V_{DD} = 1.8 to 3.6
SID44	I_{DD39}		–	–	3500	nA	V_{DD} = 3.6 to 5.5
Hibernate Mode, +105 °C							
SID42Q	I_{DD37Q}	Regulator Off.	–	–	19.4	µA	V_{DD} = 1.71 to 1.89
SID43Q	I_{DD38Q}		–	–	17	µA	V_{DD} = 1.8 to 3.6
SID44Q	I_{DD39Q}		–	–	16	µA	V_{DD} = 3.6 to 5.5
Stop Mode							
SID304	I_{DD43A}	Stop Mode current; V_{DD} = 3.6 V	–	35	85	nA	T = –40 °C to +60 °C
SID304A	I_{DD43B}	Stop Mode current; V_{DD} = 3.6 V	–	–	1450	nA	T = +85 °C
Stop Mode, +105 °C							
SID304Q	I_{DD43AQ}	Stop Mode current; V_{DD} = 3.6 V	–	–	5645	nA	
XRES current							
SID307	I_{DD_XR}	Supply current while XRES asserted	–	2	5	mA	

Table 3. AC Specifications

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details/ Conditions
SID48	F_{CPU}	CPU frequency	DC	–	48	MHz	$1.71 \le V_{DD} \le 5.5$
SID49	T_{SLEEP}	Wakeup from sleep mode	–	0	–	µs	Guaranteed by characterization
SID50	$T_{DEEPSLEEP}$	Wakeup from Deep Sleep mode	–	–	25	µs	24 MHz IMO. Guaranteed by characterization
SID51	$T_{HIBERNATE}$	Wakeup from Hibernate mode	–	–	0.7	ms	Guaranteed by characterization
SID51A	T_{STOP}	Wakeup from Stop mode	–	–	2	ms	Guaranteed by characterization
SID52	$T_{RESETWIDTH}$	External reset pulse width	1	–	–	µs	Guaranteed by characterization

GPIO

Table 4. GPIO DC Specifications

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID57	V_{IH}[2]	Input voltage high threshold	0.7 × V_{DDD}	–	–	V	CMOS Input
SID57A	IIHS	Input current when Pad > V_{DDIO} for OVT inputs	–	–	10	µA	Per I^2C Spec
SID58	V_{IL}	Input voltage low threshold	–	–	0.3 × V_{DDD}	V	CMOS Input
SID241	V_{IH}[2]	LVTTL input, V_{DDD} < 2.7 V	0.7× V_{DDD}	–	–	V	
SID242	V_{IL}	LVTTL input, V_{DDD} < 2.7 V	–	–	0.3 × V_{DDD}	V	
SID243	V_{IH}[2]	LVTTL input, $V_{DDD} \ge 2.7$ V	2.0	–	–	V	
SID244	V_{IL}	LVTTL input, $V_{DDD} \ge 2.7$ V	–	–	0.8	V	
SID59	V_{OH}	Output voltage high level	V_{DDD} –0.6	–	–	V	I_{OH} = 4 mA at 3-V V_{DDD}
SID60	V_{OH}	Output voltage high level	V_{DDD} –0.5	–	–	V	I_{OH} = 1 mA at 1.8-V V_{DDD}
SID61	V_{OL}	Output voltage low level	–	–	0.6	V	I_{OL} = 4 mA at 1.8-V V_{DDD}
SID62	V_{OL}	Output voltage low level	–	–	0.6	V	I_{OL} = 8 mA at 3-V V_{DDD}
SID62A	V_{OL}	Output voltage low level	–	–	0.4	V	I_{OL} = 3 mA at 3-V V_{DDD}
SID63	R_{PULLUP}	Pull-up resistor	3.5	5.6	8.5	kΩ	
SID64	$R_{PULLDOWN}$	Pull-down resistor	3.5	5.6	8.5	kΩ	
SID65	I_{IL}	Input leakage current (absolute value)	–	–	2	nA	25 °C, V_{DDD} = 3.0 V. Guaranteed by Characterization
SID65A	I_{IL_CTBM}	Input leakage current (absolute value) for CTBM pins	–	–	4	nA	Guaranteed by Characterization
SID66	C_{IN}	Input capacitance	–	–	7	pF	
SID67	V_{HYSTTL}	Input hysteresis LVTTL	25	40	–	mV	$V_{DDD} \ge 2.7$ V

Note
2. V_{IH} must not exceed V_{DDD} + 0.2 V.

Table 8. Opamp Specifications

(Guaranteed by Characterization) *(continued)*

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details/ Conditions
SID_DS_15	VOS_LOW_M1	Mode 1, Low current	–	5	–	mV	With trim 25 °C, 0.2 V to V_{DDA}-1.5 V
SID_DS_16	VOS_HI_M2	Mode 2, High current	–	5	–	mV	With trim 25 °C, 0.2 V to V_{DDA}-1.5 V
SID_DS_17	VOS_MED_M2	Mode 2, Medium current	–	5	–	mV	With trim 25 °C, 0.2 V to V_{DDA}-1.5 V
SID_DS_18	VOS_LOW_M2	Mode 2, Low current	–	5	–	mV	With trim 25 °C, 0.2 V to V_{DDA}-1.5 V
SID_DS_19	IOUT_HI_M1	Mode 1, High current	–	10	–	mA	Output is 0.5 V to V_{DDA}-0.5 V
SID_DS_20	IOUT_MED_M1	Mode 1, Medium current	–	10	–	mA	Output is 0.5 V to V_{DDA}-0.5 V
SID_DS_21	IOUT_LOW_M1	Mode 1, Low current	–	4	–	mA	Output is 0.5 V to V_{DDA}-0.5 V
SID_DS_22	IOUT_HI_M2	Mode 2, High current	–	1	–	mA	Output is 0.5 V to V_{DDA}-0.5 V
SID_DS_23	IOUT_MED_M2	Mode 2, Medium current	–	1	–	mA	Output is 0.5 V to V_{DDA}-0.5 V
SID_DS_24	IOUT_LOW_M2	Mode 2, Low current	–	0.5	–	mA	Output is 0.5 V to V_{DDA}-0.5 V

Comparator

Table 9. Comparator DC Specifications

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details/ Conditions
SID85	$V_{OFFSET2}$	Input offset voltage, Common Mode voltage range from 0 to V_{DD}-1	–	–	±4	mV	
SID85A	$V_{OFFSET3}$	Input offset voltage. Ultra low-power mode (V_{DDD} ≥ 2.2 V for Temp < 0 °C, V_{DDD} ≥ 1.8 V for Temp > 0 °C)	–	±12	–	mV	
SID86	V_{HYST}	Hysteresis when enabled, Common Mode voltage range from 0 to V_{DD} -1.	–	10	35	mV	Guaranteed by characterization
SID87	V_{ICM1}	Input common mode voltage in normal mode	0	–	V_{DDD} – 0.1	V	Modes 1 and 2.
SID247	V_{ICM2}	Input common mode voltage in low power mode (V_{DDD} ≥ 2.2 V for Temp < 0 °C, V_{DDD} ≥ 1.8 V for Temp > 0 °C)	0	–	V_{DDD}	V	
SID247A	V_{ICM3}	Input common mode voltage in ultra low power mode	0	–	V_{DDD} – 1.15	V	
SID88	CMRR	Common mode rejection ratio	50	–	–	dB	V_{DDD} ≥ 2.7 V. Guaranteed by characterization
SID88A	CMRR	Common mode rejection ratio	42	–	–	dB	V_{DDD} < 2.7 V. Guaranteed by characterization
SID89	I_{CMP1}	Block current, normal mode	–	–	400	µA	Guaranteed by characterization

Table 13. SAR ADC AC Specifications

(Guaranteed by Characterization)

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID106	A_PSRR	Power supply rejection ratio	70	–	–	dB	
SID107	A_CMRR	Common mode rejection ratio	66	–	–	dB	Measured at 1 V
SID108	A_SAMP_1	Sample rate with external reference bypass cap	–	–	1	Msps	
SID108A	A_SAMP_2	Sample rate with no bypass cap. Reference = V_{DD}	–	–	1	Msps	
SID108B	A_SAMP_3	Sample rate with no bypass cap. Internal reference	–	–	100	Ksps	
SID109	A_SNDR	Signal-to-noise and distortion ratio (SINAD)	66	–	–	dB	F_{IN} = 10 kHz
SID111	A_INL	Integral non linearity	–1.4	–	+1.4	LSB	V_{DD} = 1.71 to 5.5, 1 Msps, Vref = 1 to 5.5.
SID111A	A_INL	Integral non linearity	–1.4	–	+1.4	LSB	V_{DDD} = 1.71 to 3.6, 1 Msps, Vref = 1.71 to V_{DDD}.
SID111B	A_INL	Integral non linearity	–1.4	–	+1.4	LSB	V_{DDD} = 1.71 to 5.5, 500 ksps, Vref = 1 to 5.5.
SID112	A_DNL	Differential non linearity	–0.9	–	+1.35	LSB	V_{DDD} = 1.71 to 5.5, 1 Msps, Vref = 1 to 5.5.
SID112A	A_DNL	Differential non linearity	–0.9	–	+1.35	LSB	V_{DDD} = 1.71 to 3.6, 1 Msps, Vref = 1.71 to V_{DDD}.
SID112B	A_DNL	Differential non linearity	–0.9	–	+1.35	LSB	V_{DDD} = 1.71 to 5.5, 500 ksps, Vref = 1 to 5.5.
SID113	A_THD	Total harmonic distortion	–	–	–65	dB	F_{IN} = 10 kHz.

CSD

Table 14. CSD Block Specification

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
CSD Specification							
SID308	VCSD	Voltage range of operation	1.71	–	5.5	V	
SID309	IDAC1	DNL for 8-bit resolution	–1	–	1	LSB	
SID310	IDAC1	INL for 8-bit resolution	–3	–	3	LSB	
SID311	IDAC2	DNL for 7-bit resolution	–1	–	1	LSB	
SID312	IDAC2	INL for 7-bit resolution	–3	–	3	LSB	
SID313	SNR	Ratio of counts of finger to noise. Guaranteed by characterization	5	–	–	Ratio	Capacitance range of 9 to 35 pF, 0.1-pF sensitivity
SID314	IDAC1_CRT1	Output current of Idac1 (8-bits) in High range	–	612	–	µA	
SID314A	IDAC1_CRT2	Output current of Idac1(8-bits) in Low range	–	306	–	µA	
SID315	IDAC2_CRT1	Output current of Idac2 (7-bits) in High range	–	304.8	–	µA	
SID315A	IDAC2_CRT2	Output current of Idac2 (7-bits) in Low range	–	152.4	–	µA	

LCD Direct Drive

Table 18. LCD Direct Drive DC Specifications

(Guaranteed by Characterization)

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID154	I_{LCDLOW}	Operating current in low power mode	–	5	–	µA	16 × 4 small segment disp. at 50 Hz
SID155	C_{LCDCAP}	LCD capacitance per segment/common driver	–	500	5000	pF	Guaranteed by Design
SID156	LCD_{OFFSET}	Long-term segment offset	–	20	–	mV	
SID157	I_{LCDOP1}	PWM Mode current. 5-V bias. 24-MHz IMO	–	0.6	–	mA	32 × 4 segments. 50 Hz, 25 °C
SID158	I_{LCDOP2}	PWM Mode current. 3.3-V bias. 24-MHz IMO.	–	0.5	–	mA	32 × 4 segments. 50 Hz, 25 °C

Table 19. LCD Direct Drive AC Specifications

(Guaranteed by Characterization)

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID159	F_{LCD}	LCD frame rate	10	50	150	Hz	

Table 20. Fixed UART DC Specifications

(Guaranteed by Characterization)

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID160	I_{UART1}	Block current consumption at 100 Kbps	–	–	55	µA	
SID161	I_{UART2}	Block current consumption at 1000 Kbps	–	–	312	µA	

Table 21. Fixed UART AC Specifications

(Guaranteed by Characterization)

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID162	F_{UART}	Bit rate	–	–	1	Mbps	

SPI Specifications

Table 22. Fixed SPI DC Specifications

(Guaranteed by Characterization)

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID163	I_{SPI1}	Block current consumption at 1 Mbps	–	–	360	µA	
SID164	I_{SPI2}	Block current consumption at 4 Mbps	–	–	560	µA	
SID165	I_{SPI3}	Block current consumption at 8 Mbps	–	–	600	µA	

Table 23. Fixed SPI AC Specifications

(Guaranteed by Characterization)

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID166	F_{SPI}	SPI operating frequency (master; 6X oversampling)	–	–	8	MHz	

Table 24. Fixed SPI Master mode AC Specifications

(Guaranteed by Characterization)

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID167	T_{DMO}	MOSI valid after Sclock driving edge	–	–	15	ns	
SID168	T_{DSI}	MISO valid before Sclock capturing edge. Full clock, late MISO Sampling used	20	–	–	ns	
SID169	T_{HMO}	Previous MOSI data hold time with respect to capturing edge at Slave	0	–	–	ns	

Table 25. Fixed SPI Slave mode AC Specifications

(Guaranteed by Characterization)

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID170	T_{DMI}	MOSI valid before Sclock capturing edge	40	–	–	ns	
SID171	T_{DSO}	MISO valid after Sclock driving edge	–	–	42 + 3 × (1/FCPU)	ns	
SID171A	T_{DSO_ext}	MISO valid after Sclock driving edge in Ext. Clock mode	–	–	48	ns	
SID172	T_{HSO}	Previous MISO data hold time	0	–	–	ns	
SID172A	$T_{SSELSCK}$	SSEL Valid to first SCK Valid edge	100	–	–	ns	

Memory

Table 26. Flash DC Specifications

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID173	V_{PE}	Erase and program voltage	1.71	–	5.5	V	

Table 27. Flash AC Specifications

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID174	$T_{ROWWRITE}$	Row (block) write time (erase and program)	–	–	20	ms	Row (block) = 128 bytes
SID175	$T_{ROWERASE}$	Row erase time	–	–	13	ms	
SID176	$T_{ROWPROGRAM}$	Row program time after erase	–	–	7	ms	
SID178	$T_{BULKERASE}$	Bulk erase time (128 KB)	–	–	35	ms	
SID179	$T_{SECTORERASE}$	Sector erase time (8 KB)	–	–	15	ms	
SID180	$T_{DEVPROG}$	Total device program time	–	–	15	seconds	Guaranteed by characterization
SID181	F_{END}	Flash endurance	100 K	–	–	cycles	Guaranteed by characterization
SID182	F_{RET}	Flash retention. $T_A \le 55$ °C, 100 K P/E cycles	20	–	–	years	Guaranteed by characterization
SID182A		Flash retention. $T_A \le 85$ °C, 10 K P/E cycles	10	–	–	years	Guaranteed by characterization
SID182B	F_{RETQ}	Flash retention. $T_A \le 105$ °C, 10K P/E cycles, ≤ three years at $T_A \ge 85$ °C	10	20	–	years	Guaranteed by characterization.

System Resources

Power-on-Reset (POR) with Brown Out

Table 28. Imprecise Power On Reset (PRES)

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID185	$V_{RISEIPOR}$	Rising trip voltage	0.80	–	1.45	V	Guaranteed by characterization
SID186	$V_{FALLIPOR}$	Falling trip voltage	0.75	–	1.4	V	Guaranteed by characterization
SID187	$V_{IPORHYST}$	Hysteresis	15	–	200	mV	Guaranteed by characterization

Table 29. Precise Power On Reset (POR)

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID190	$V_{FALLPPOR}$	BOD trip voltage in active and sleep modes	1.64	–	–	V	Guaranteed by characterization
SID192	$V_{FALLDPSLP}$	BOD trip voltage in Deep Sleep	1.4	–	–	V	Guaranteed by characterization

Voltage Monitors

Table 30. Voltage Monitors DC Specifications

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID195	V_{LVI1}	LVI_A/D_SEL[3:0] = 0000b	1.71	1.75	1.79	V	
SID196	V_{LVI2}	LVI_A/D_SEL[3:0] = 0001b	1.76	1.80	1.85	V	
SID197	V_{LVI3}	LVI_A/D_SEL[3:0] = 0010b	1.85	1.90	1.95	V	
SID198	V_{LVI4}	LVI_A/D_SEL[3:0] = 0011b	1.95	2.00	2.05	V	
SID199	V_{LVI5}	LVI_A/D_SEL[3:0] = 0100b	2.05	2.10	2.15	V	
SID200	V_{LVI6}	LVI_A/D_SEL[3:0] = 0101b	2.15	2.20	2.26	V	
SID201	V_{LVI7}	LVI_A/D_SEL[3:0] = 0110b	2.24	2.30	2.36	V	
SID202	V_{LVI8}	LVI_A/D_SEL[3:0] = 0111b	2.34	2.40	2.46	V	
SID203	V_{LVI9}	LVI_A/D_SEL[3:0] = 1000b	2.44	2.50	2.56	V	
SID204	V_{LVI10}	LVI_A/D_SEL[3:0] = 1001b	2.54	2.60	2.67	V	
SID205	V_{LVI11}	LVI_A/D_SEL[3:0] = 1010b	2.63	2.70	2.77	V	
SID206	V_{LVI12}	LVI_A/D_SEL[3:0] = 1011b	2.73	2.80	2.87	V	
SID207	V_{LVI13}	LVI_A/D_SEL[3:0] = 1100b	2.83	2.90	2.97	V	
SID208	V_{LVI14}	LVI_A/D_SEL[3:0] = 1101b	2.93	3.00	3.08	V	
SID209	V_{LVI15}	LVI_A/D_SEL[3:0] = 1110b	3.12	3.20	3.28	V	
SID210	V_{LVI16}	LVI_A/D_SEL[3:0] = 1111b	4.39	4.50	4.61	V	
SID211	LVI_IDD	Block current	–	–	100	µA	Guaranteed by characterization

Table 31. Voltage Monitors AC Specifications

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID212	$T_{MONTRIP}$	Voltage monitor trip time	–	–	1	µs	Guaranteed by characterization

SWD Interface

Table 32. SWD Interface Specifications

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID213	F_SWDCLK1	3.3 V ≤ V_{DD} ≤ 5.5 V	–	–	14	MHz	SWDCLK ≤ 1/3 CPU clock frequency
SID214	F_SWDCLK2	1.71 V ≤ V_{DD} ≤ 3.3 V	–	–	7	MHz	SWDCLK ≤ 1/3 CPU clock frequency
SID215	T_SWDI_SETUP	T = 1/f SWDCLK	0.25*T	–	–	ns	Guaranteed by characterization
SID216	T_SWDI_HOLD	T = 1/f SWDCLK	0.25*T	–	–	ns	Guaranteed by characterization
SID217	T_SWDO_VALID	T = 1/f SWDCLK	–	–	0.5*T	ns	Guaranteed by characterization
SID217A	T_SWDO_HOLD	T = 1/f SWDCLK	1	–	–	ns	Guaranteed by characterization

Internal Main Oscillator

Table 33. IMO DC Specifications

(Guaranteed by Design)

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID218	I_{IMO1}	IMO operating current at 48 MHz	–	–	1000	µA	
SID219	I_{IMO2}	IMO operating current at 24 MHz	–	–	325	µA	
SID220	I_{IMO3}	IMO operating current at 12 MHz	–	–	225	µA	
SID221	I_{IMO4}	IMO operating current at 6 MHz	–	–	180	µA	
SID222	I_{IMO5}	IMO operating current at 3 MHz	–	–	150	µA	

Table 34. IMO AC Specifications

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID223	$F_{IMOTOL1}$	Frequency variation from 3 to 48 MHz	–	–	±2	%	±3% if T_A > 85 °C and IMO frequency < 24 MHz
SID226	$T_{STARTIMO}$	IMO startup time	–	–	12	µs	
SID227	$T_{JITRMSIMO1}$	RMS Jitter at 3 MHz	–	156	–	ps	
SID228	$T_{JITRMSIMO2}$	RMS Jitter at 24 MHz	–	145	–	ps	
SID229	$T_{JITRMSIMO3}$	RMS Jitter at 48 MHz	–	139	–	ps	

Internal Low-Speed Oscillator

Table 35. ILO DC Specifications

(Guaranteed by Design)

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID231	I_{ILO1}	ILO operating current at 32 kHz	–	0.3	1.05	µA	Guaranteed by Characterization
SID233	$I_{ILOLEAK}$	ILO leakage current	–	2	15	nA	Guaranteed by Design

Ordering Information

The PSoC 4200M family part numbers and features are listed in the following table.

Category	MPN	Features														Packages			
		Max CPU Speed (MHz)	Flash (KB)	SRAM (KB)	UDB	Opamp (CTBm)	CSD	IDAC (1X7-Bit, 1-8-Bit)	Direct LCD Drive	12-bit SAR ADC	LP Comparators	TCPWM Blocks	SCB Blocks	CAN	GPIO	48-TQFP	64-TQFP (0.5-mm pitch)	64-TQFP (0.8-mm pitch)	68-QFN
4245	CY8C4245AZI-M433	48	32	4	4	2	–	–	–	1000 ksps	2	8	4	–	38	✔	–	–	–
	CY8C4245AZI-M443	48	32	4	4	2	✔	–	✔	1000 ksps	2	8	4	–	38	✔	–	–	–
	CY8C4245AZI-M445	48	32	4	4	2	✔	–	✔	1000 ksps	2	8	4	–	51	–	✔	–	–
	CY8C4245LTI-M445	48	32	4	4	2	✔	–	✔	1000 ksps	2	8	4	–	55	–	–	–	✔
	CY8C4245AXI-M445	48	32	4	4	2	✔	–	✔	1000 ksps	2	8	4	–	51	–	–	✔	–
4246	CY8C4246AZI-M443	48	64	8	4	2	✔	–	✔	1000 ksps	2	8	4	–	38	✔	–	–	–
	CY8C4246AZI-M445	48	64	8	4	2	✔	–	✔	1000 ksps	2	8	4	–	51	–	✔	–	–
	CY8C4246AZI-M475	48	64	8	4	4	–	✔	–	1000 ksps	2	8	4	–	51	–	✔	–	–
	CY8C4246LTI-M445	48	64	8	4	2	✔	–	✔	1000 ksps	2	8	4	–	55	–	–	–	✔
	CY8C4246LTI-M475	48	64	8	4	4	–	✔	–	1000 ksps	2	8	4	–	55	–	–	–	✔
	CY8C4246AXI-M445	48	64	8	4	2	✔	–	✔	1000 ksps	2	8	4	–	51	–	–	✔	–
4247	CY8C4247LTI-M475	48	128	16	4	4	✔	✔	–	1000 ksps	2	8	4	–	55	–	–	–	✔
	CY8C4247AZI-M475	48	128	16	4	4	–	✔	–	1000 ksps	2	8	4	–	51	–	✔	–	–
	CY8C4247AZI-M485	48	128	16	4	4	✔	✔	✔	1000 ksps	2	8	4	✔	51	–	✔	–	–
	CY8C4247AXI-M485	48	128	16	4	4	✔	✔	✔	1000 ksps	2	8	4	✔	51	–	–	✔	–
	CY8C4247LTQ-M475	48	128	16	4	4	✔	✔	✔	1000 ksps	2	8	4	–	55	–	–	–	✔

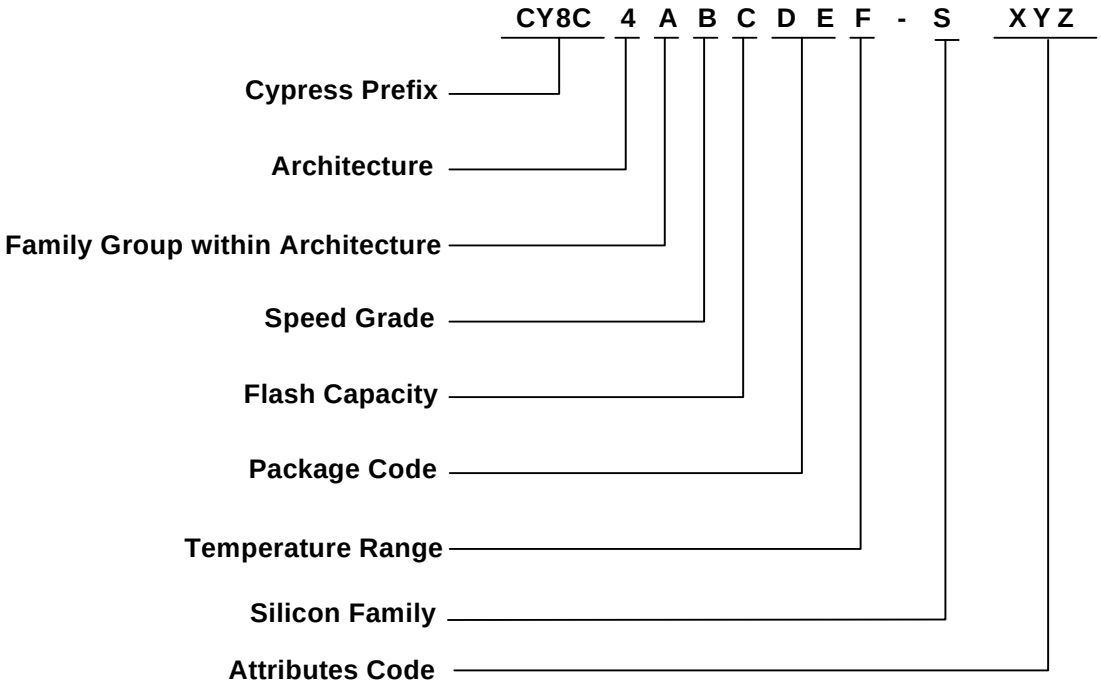
The nomenclature used in the preceding table is based on the following part numbering convention:

Field	Description	Values	Meaning
CY8C	Cypress Prefix		
4	Architecture	4	PSoC 4
A	Family	2	4200 Family
B	CPU Speed	4	48 MHz
C	Flash Capacity	4	16 KB
		5	32 KB
		6	64 KB
		7	128 KB
DE	Package Code	AX, AZ	TQFP
		LT	QFN
		BU	BGA
		FD	CSP

Field	Description	Values	Meaning
F	Temperature Range	I	Industrial
		Q	Extended Industrial
S	Silicon Family	N/A	PSoC 4 Base Series
		L	PSoC 4 L-Series
		BL	PSoC 4 BLE
		M	PSoC 4 M-Series
XYZ	Attributes Code	000-999	Code of feature set in the specific family

Part Numbering Conventions

The part number fields are defined as follows.



Packaging

The description of the PSoC4200M package dimensions follows.

Spec ID#	Package	Description	Package Dwg #
PKG_1	68-pin QFN	68-pin QFN, 8 mm x 8 mm x 1.0 mm height with 0.4 mm pitch	001-09618
PKG_2	64-pin TQFP	64-pin TQFP, 10 mm x10 mm x 1.4 mm height with 0.5 mm pitch	51-85051
PKG_4	64-pin TQFP	64-pin TQFP, 14 mm x14 mm x 1.4 mm height with 0.8 mm pitch	51-85046
PKG_5	48-pin TQFP	48-pin TQFP, 7 mm x 7 mm x 1.4 mm height with 0.5 mm pitch	51-85135
PKG_6	44-pin TQFP	44-pin TQFP, 10 mm x 10 mm x 1.4 mm height with 0.8 mm pitch	51-85064

Table 43. Package Characteristics

Parameter	Description	Conditions	Min	Typ	Max	Units
T_A	Operating ambient temperature		–40	25	85	°C
T_J	Operating junction temperature		–40		100	°C
T_{JA}	Package θ_{JA} (68-pin QFN)		–	16.8	–	°C/Watt
T_{JC}	Package θ_{JC} (68-pin QFN)		–	2.9	–	°C/Watt
T_{JA}	Package θ_{JA} (64-pin TQFP, 0.5-mm pitch)		–	56	–	°C/Watt
T_{JC}	Package θ_{JC} (64-pin TQFP, 0.5-mm pitch)		–	19.5	–	°C/Watt
T_{JA}	Package θ_{JA} (64-pin TQFP, 0.8-mm pitch)		–	66.4	–	°C/Watt
T_{JC}	Package θ_{JC} (64-pin TQFP, 0.8-mm pitch)		–	18.2	–	°C/Watt
T_{JA}	Package θ_{JA} (48-pin TQFP, 0.5-mm pitch)		–	67.3	–	°C/Watt
T_{JC}	Package θ_{JC} (48-pin TQFP, 0.5-mm pitch)		–	30.4	–	°C/Watt
T_{JA}	Package θ_{JA} (44-pin TQFP, 0.8-mm pitch)		–	57	–	°C/Watt
T_{JC}	Package θ_{JC} (44-pin TQFP, 0.8-mm pitch)		–	25.9	–	°C/Watt

Table 44. Solder Reflow Peak Temperature

Package	Maximum Peak Temperature	Maximum Time at Peak Temperature
All packages	260 °C	30 seconds

Table 45. Package Moisture Sensitivity Level (MSL), IPC/JEDEC J-STD-2

Package	MSL
All packages	MSL 3

Acronyms

Table 46. Acronyms Used in this Document

Acronym	Description
abus	analog local bus
ADC	analog-to-digital converter
AG	analog global
AHB	AMBA (advanced microcontroller bus architecture) high-performance bus, an ARM data transfer bus
ALU	arithmetic logic unit
AMUXBUS	analog multiplexer bus
API	application programming interface
APSR	application program status register
ARM®	advanced RISC machine, a CPU architecture
ATM	automatic thump mode
BW	bandwidth
CAN	Controller Area Network, a communications protocol
CMRR	common-mode rejection ratio
CPU	central processing unit
CRC	cyclic redundancy check, an error-checking protocol
DAC	digital-to-analog converter, see also IDAC, VDAC
DFB	digital filter block
DIO	digital input/output, GPIO with only digital capabilities, no analog. See GPIO.
DMIPS	Dhrystone million instructions per second
DMA	direct memory access, see also TD
DNL	differential nonlinearity, see also INL
DNU	do not use
DR	port write data registers
DSI	digital system interconnect
DWT	data watchpoint and trace
ECC	error correcting code
ECO	external crystal oscillator
EEPROM	electrically erasable programmable read-only memory
EMI	electromagnetic interference
EMIF	external memory interface
EOC	end of conversion
EOF	end of frame
EPSR	execution program status register
ESD	electrostatic discharge

Table 46. Acronyms Used in this Document *(continued)*

Acronym	Description
ETM	embedded trace macrocell
FIR	finite impulse response, see also IIR
FPB	flash patch and breakpoint
FS	full-speed
GPIO	general-purpose input/output, applies to a PSoC pin
HVI	high-voltage interrupt, see also LVI, LVD
IC	integrated circuit
IDAC	current DAC, see also DAC, VDAC
IDE	integrated development environment
I^2C, or IIC	Inter-Integrated Circuit, a communications protocol
IIR	infinite impulse response, see also FIR
ILO	internal low-speed oscillator, see also IMO
IMO	internal main oscillator, see also ILO
INL	integral nonlinearity, see also DNL
I/O	input/output, see also GPIO, DIO, SIO, USBIO
IPOR	initial power-on reset
IPSR	interrupt program status register
IRQ	interrupt request
ITM	instrumentation trace macrocell
LCD	liquid crystal display
LIN	Local Interconnect Network, a communications protocol.
LR	link register
LUT	lookup table
LVD	low-voltage detect, see also LVI
LVI	low-voltage interrupt, see also HVI
LVTTL	low-voltage transistor-transistor logic
MAC	multiply-accumulate
MCU	microcontroller unit
MISO	master-in slave-out
NC	no connect
NMI	nonmaskable interrupt
NRZ	non-return-to-zero
NVIC	nested vectored interrupt controller
NVL	nonvolatile latch, see also WOL
opamp	operational amplifier
PAL	programmable array logic, see also PLD
PC	program counter
PCB	printed circuit board

Document Conventions

Units of Measure

Table 47. Units of Measure

Symbol	Unit of Measure
°C	degrees Celsius
dB	decibel
fF	femto farad
Hz	hertz
KB	1024 bytes
kbps	kilobits per second
Khr	kilohour
kHz	kilohertz
kΩ	kilo ohm
ksps	kilosamples per second
LSB	least significant bit
Mbps	megabits per second
MHz	megahertz
MΩ	mega-ohm
Msps	megasamples per second
µA	microampere
µF	microfarad
µH	microhenry
µs	microsecond
µV	microvolt
µW	microwatt
mA	milliampere
ms	millisecond
mV	millivolt
nA	nanoampere
ns	nanosecond
nV	nanovolt
Ω	ohm
pF	picofarad
ppm	parts per million
ps	picosecond
s	second
sps	samples per second
sqrtHz	square root of hertz
V	volt